

CERN

European Organization for Nuclear Research

Organisation Européenne pour la Recherche Nucléaire

## From High Energy Physics to Industry: application of CERN microelectronics outside HEP

*Pierre Jarron*  
*CERN PH*

# OUTLINE

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## *CERN microelectronics*

- Focus and activities

## *CERN ASICs*

- Sensors interface, front end
- Signal processing
- Power systems

## *Fields of applications*

- Medical imaging
- Life science
- Industry

## *Technology transfer approaches*



# CERN focus of HEP ASIC R&D

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## *The last 15 years*

- Develop ASICs for LHC experiments
  - Analog and mixed signal front end circuits interfacing sensors
  - Signal processing and optoelectronics circuits
- Develop radiation tolerance of ICs
  - Based on industrial microelectronics processes
    - Bipolar, BiCMOS, CMOS 0.25 $\mu$ m and 0.13 $\mu$ m
  - Partnership with semiconductor industry
    - In foundry service : IBM, ATMEL
    - Development of products with ST Microelectronics: voltage regulator, ASIC with ADC
- Design issues of sensor electronics,
  - Complex low power low noise mixed-signal circuits ASICs
    - High channel density: strip detector
    - Very high packing density: pixel detector
    - Ultra fast electronics: Time-of-Flight detector



# Technology transfer of HEP ASICs

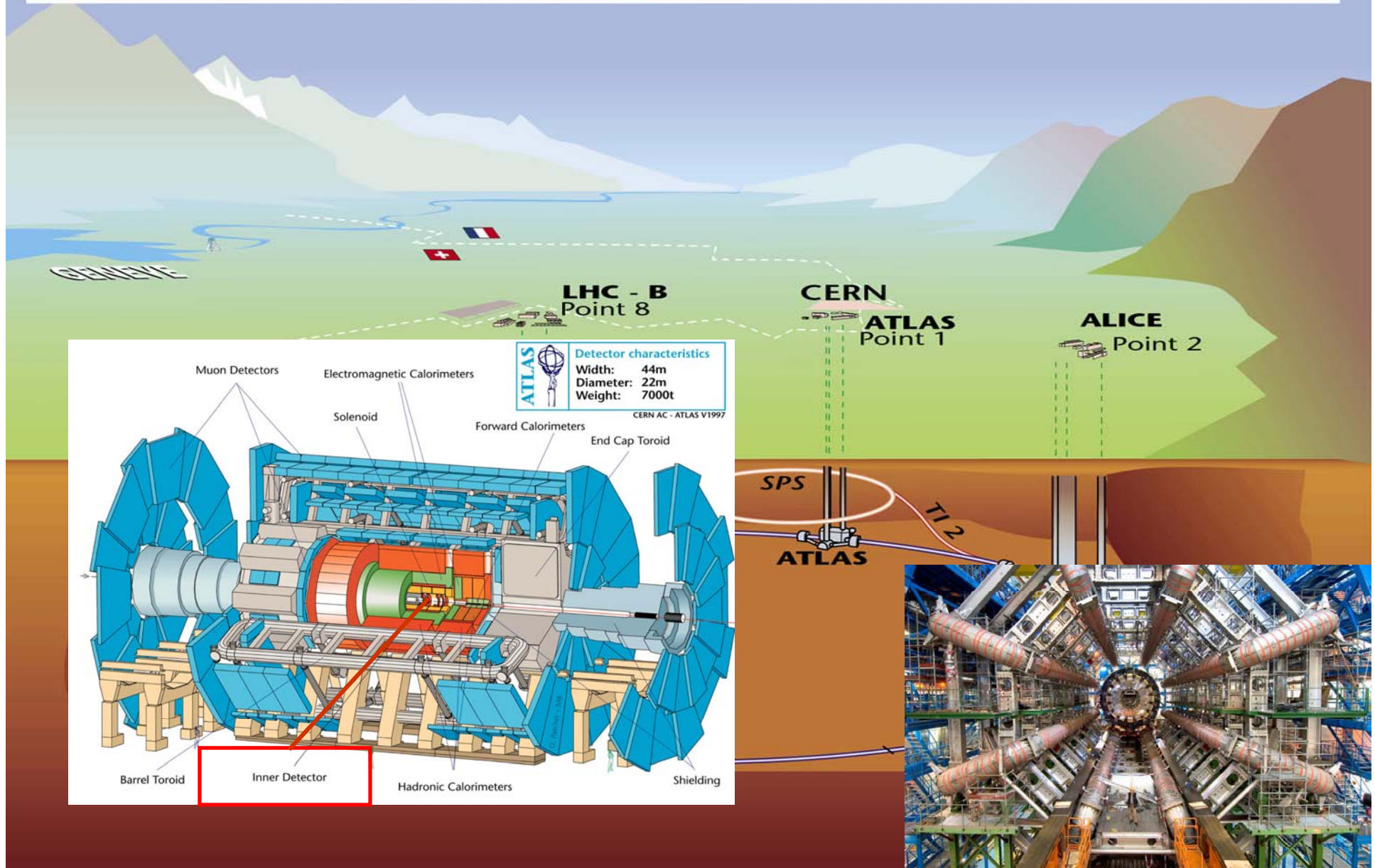
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## *4 technologies presented*

- Linear multi-channel arrays
  - ATLAS SCT silicon tracker
- Pixel arrays
  - ALICE and LHCb pixel detector
- Ultra fast ASIC channel
  - ALICE TOF detector
- Radiation hardening
  - Radiation hard ASIC



# Overall view of the LHC experiments.

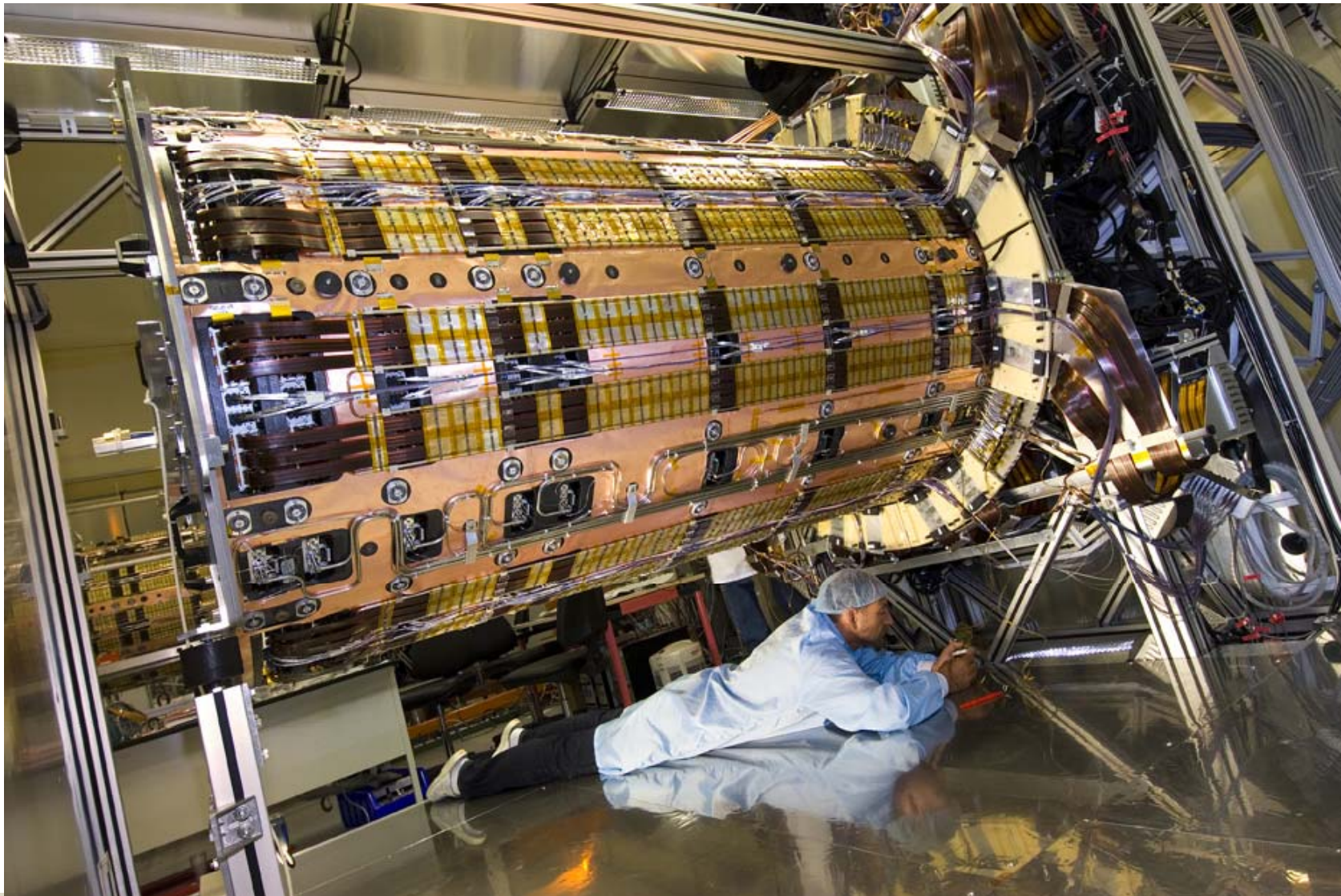


Readout Electronics Business Briefing  
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Physics  
 Department



# ATLAS SCT barrel detector

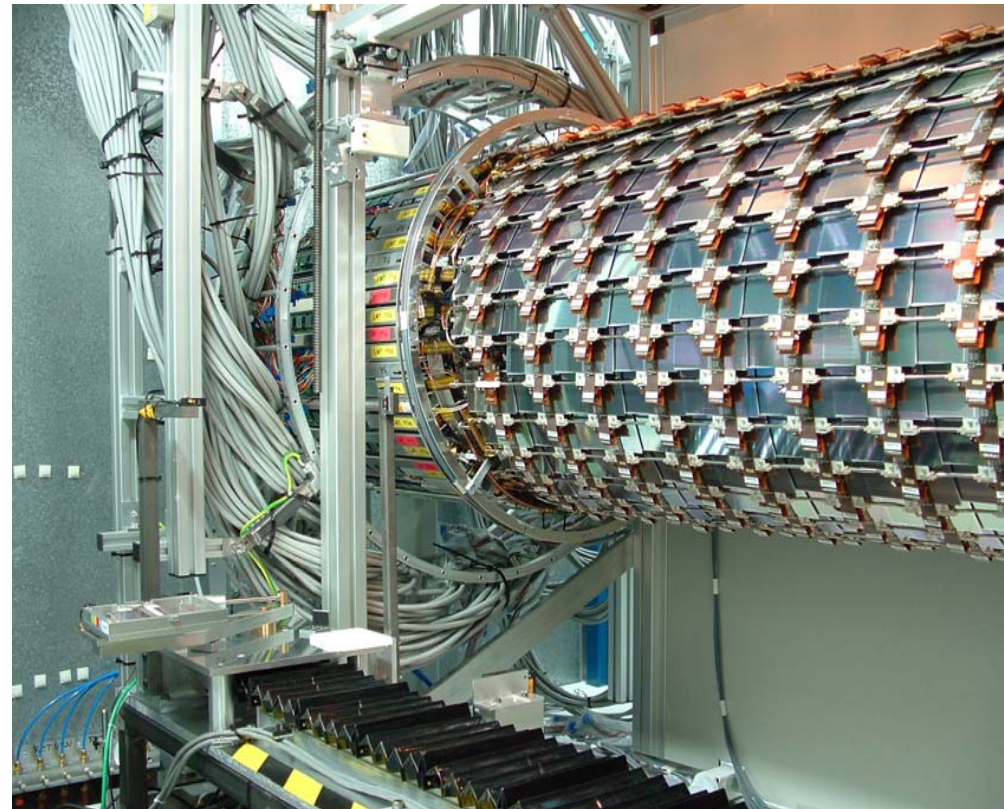
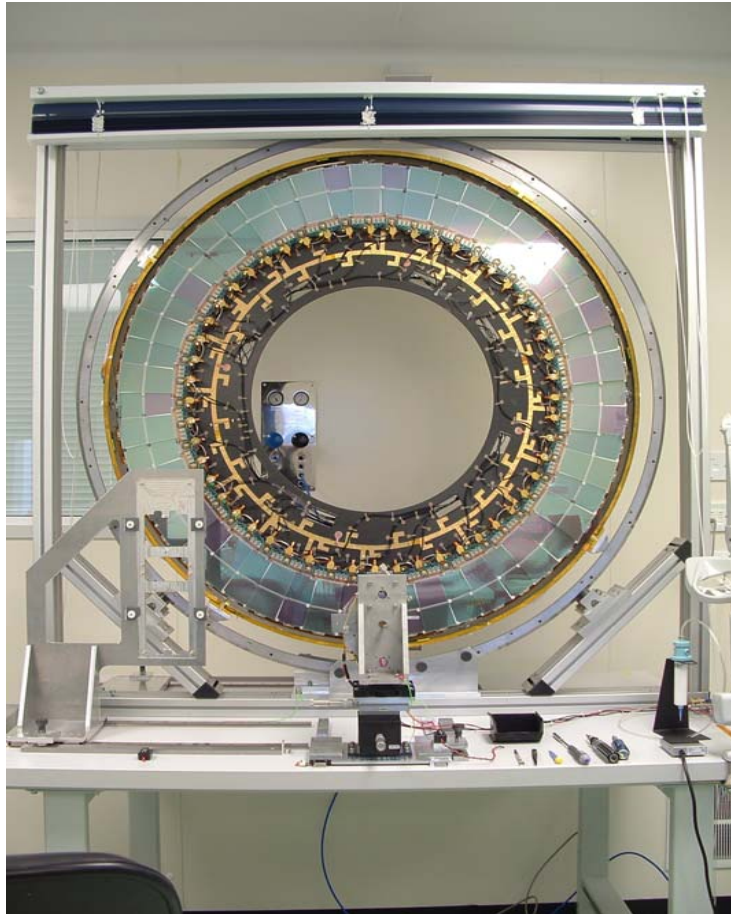


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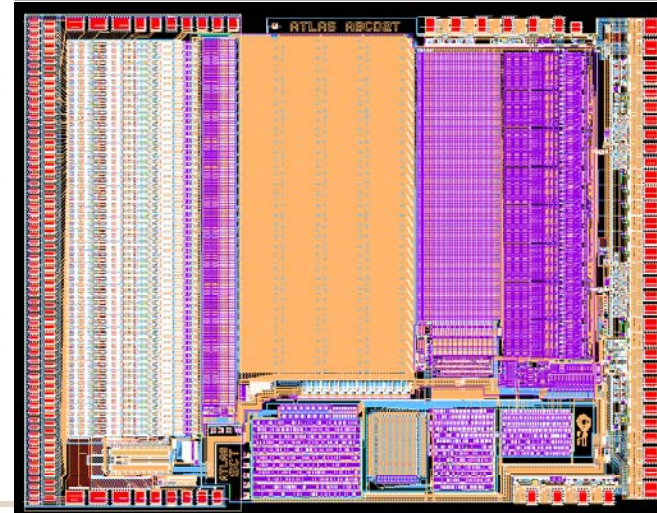
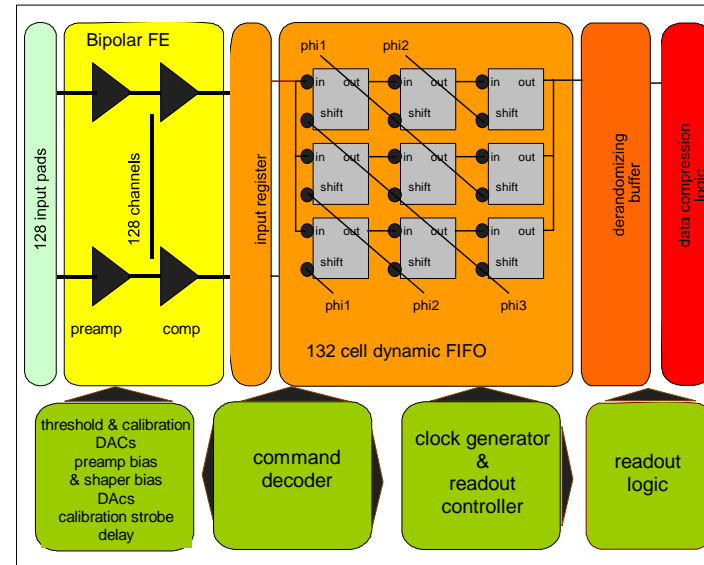
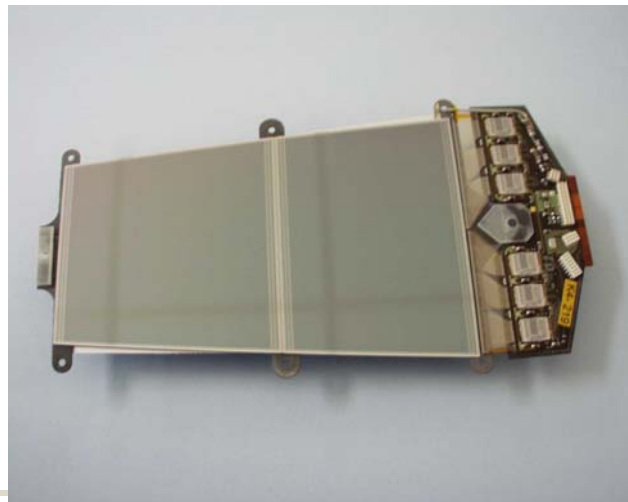
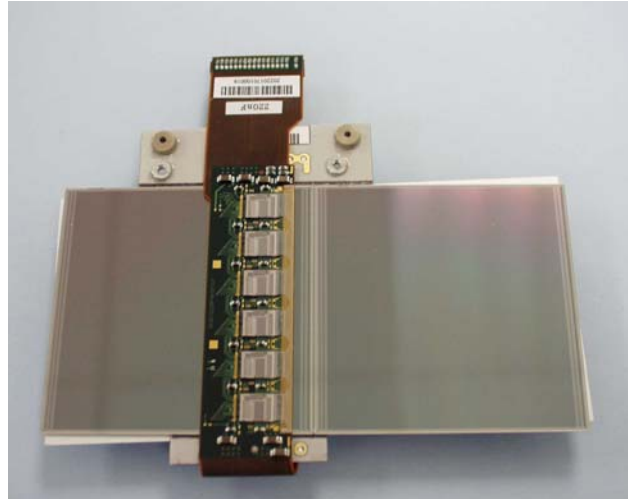


# ATLAS SCT Tracker



# ATLAS SCT detector modules

*Forward and Barrel modules, principle and die*



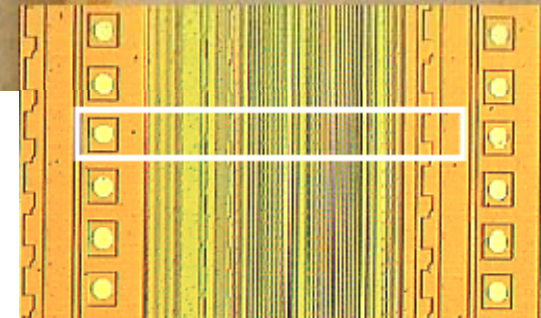
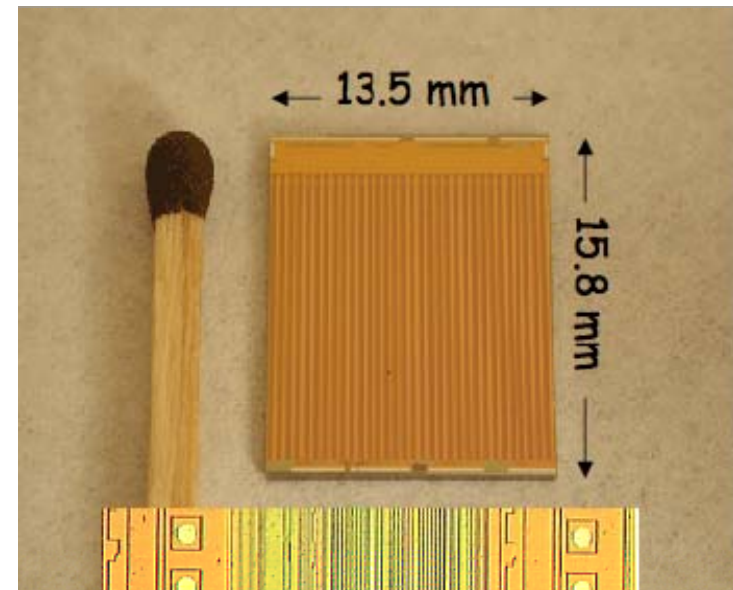
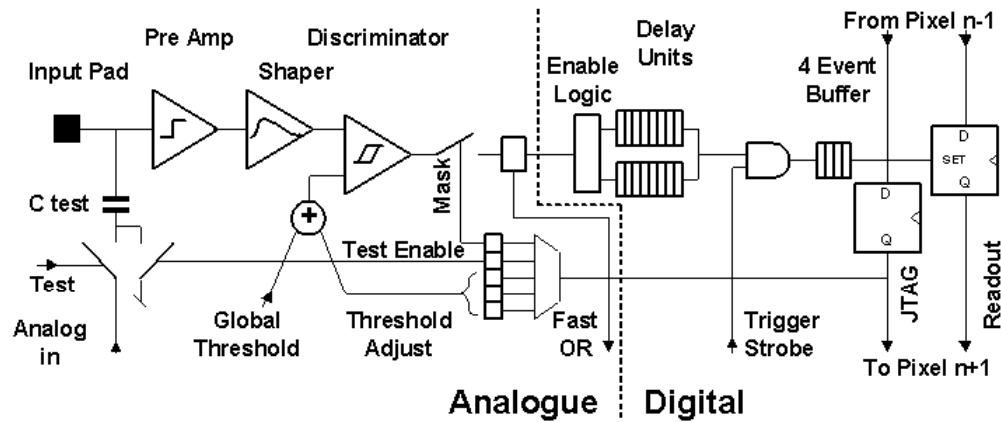
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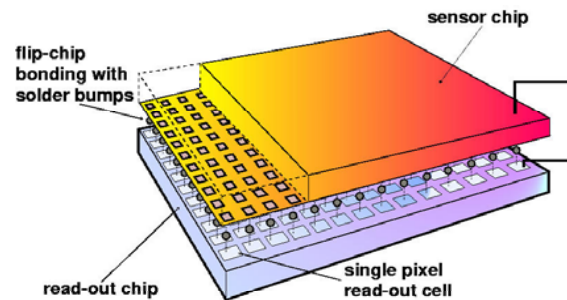


# ALICE pixel detector

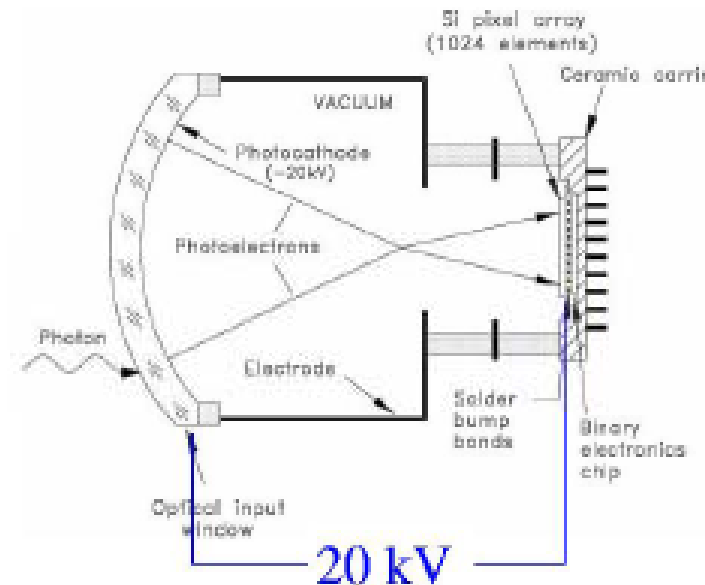
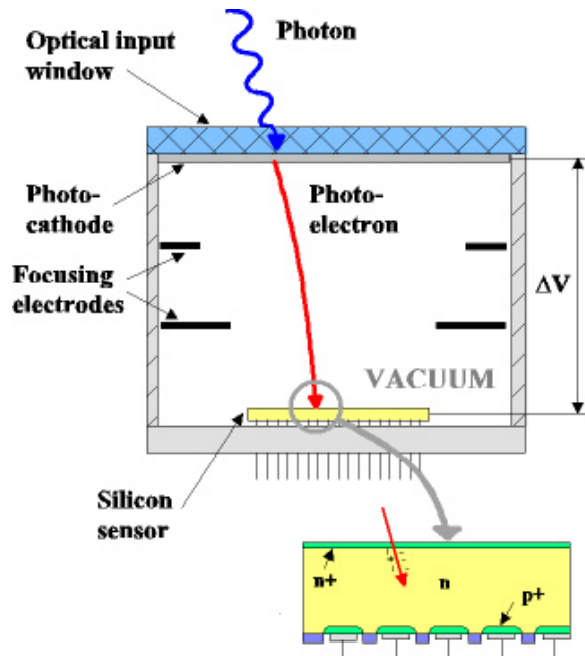
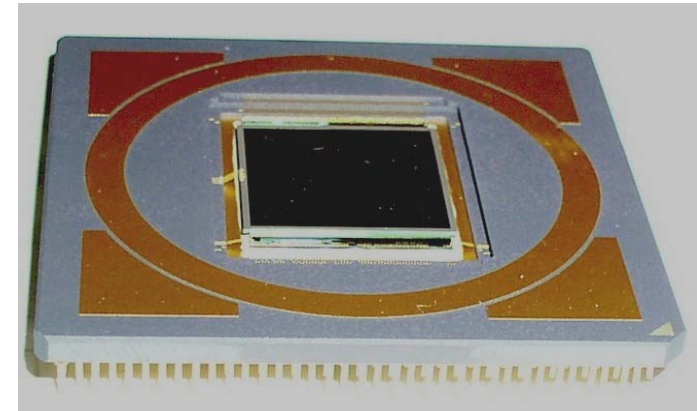
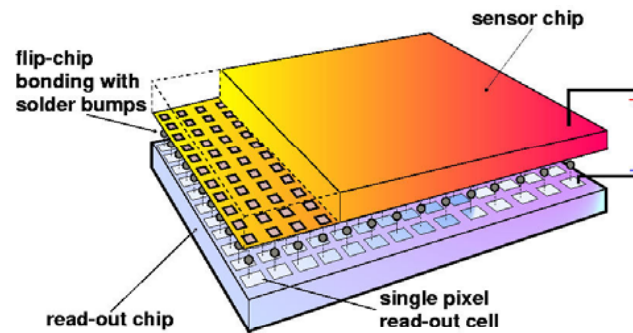
## Principle & die



- CMOS6 0.25  $\mu\text{m}$  (8" wafers)
- Radiation hard design (enclosed transistors)
- $\approx 13 \cdot 10^6$  transistors
- 8192 pixel cells 50  $\mu\text{m}$  x 425  $\mu\text{m}$
- 256 rows, 32 columns
- Active area: 12.8mm x 13.6mm
- 10 MHz clock
- 1.8V power supply
- $\sim 100 \mu\text{W}/\text{channel}$



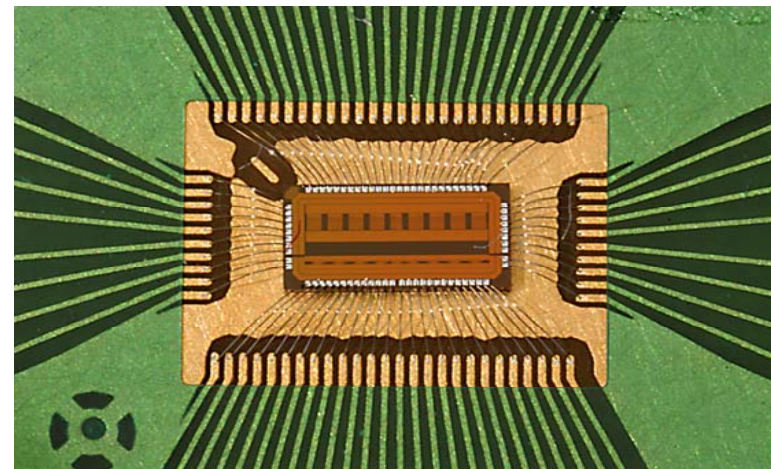
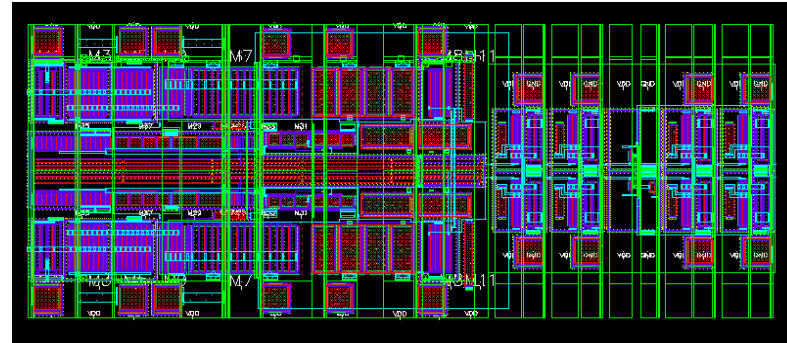
# LHCb pixel HPD: a true single visible photon imager



# ALICE Time-of-Flight ASIC: NINO front end

## *NINO 8-channels*

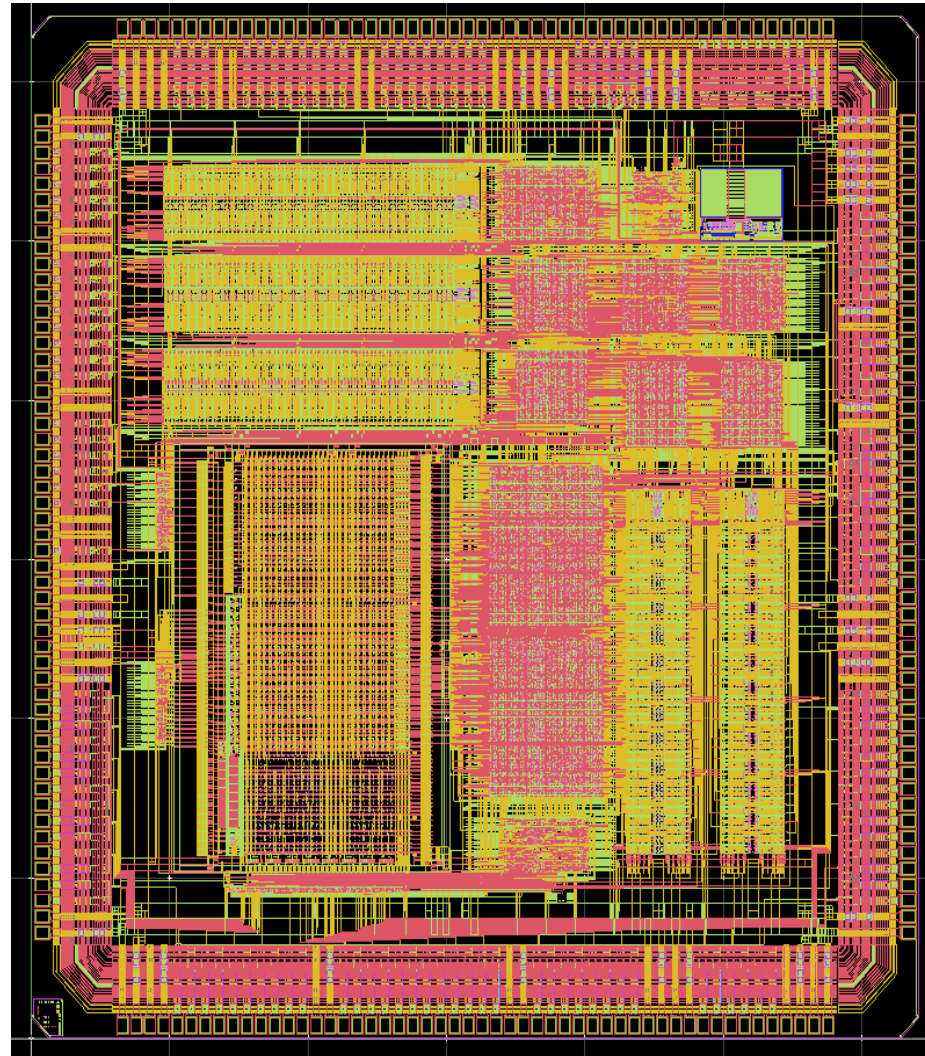
- an ultra-fast, low-power, front-end amplifier discriminator for the Time-Of-Flight experiment in ALICE
- 3 Ghz preamplifier bandwidth
- Measure timing with 20 ps resolution
- 25 000 chips for ALICE TOF Pion-Kaon identification





# ALICE Time-of-Flight ASIC: TDC

- ◆ Time-to-Digital Converter
  - ◆ 0.25 mm CMOS
  - ◆ Semi-Custom
    - ◆ PLL @ 320 MHz
    - ◆ 4 Memory blocks
    - ◆ DLL and Hit registers
  - ◆ 32 channels, 25 and 100 ps resolution
  - ◆ 3.3 V I/O, 2.5V core
- ◆ 5.5x5.5 mm<sup>2</sup>
- ◆ Used also in industry outside HEP



# Front end design, other examples

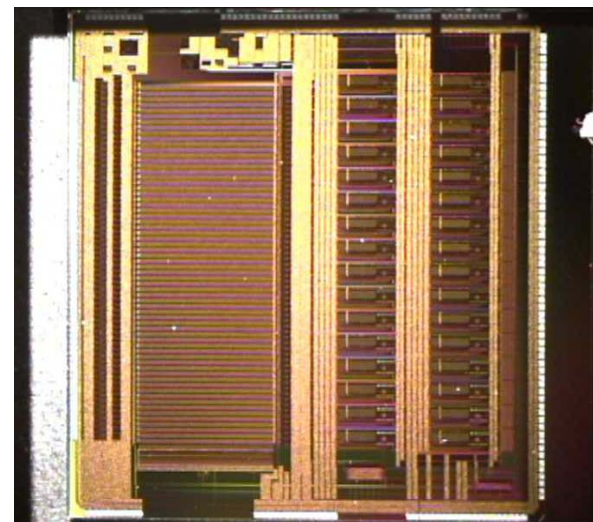
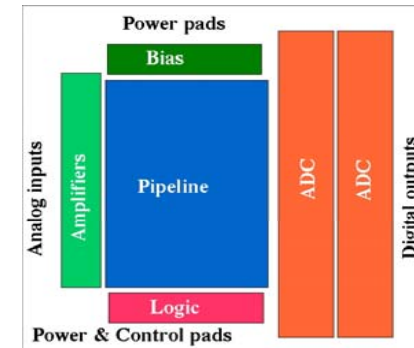
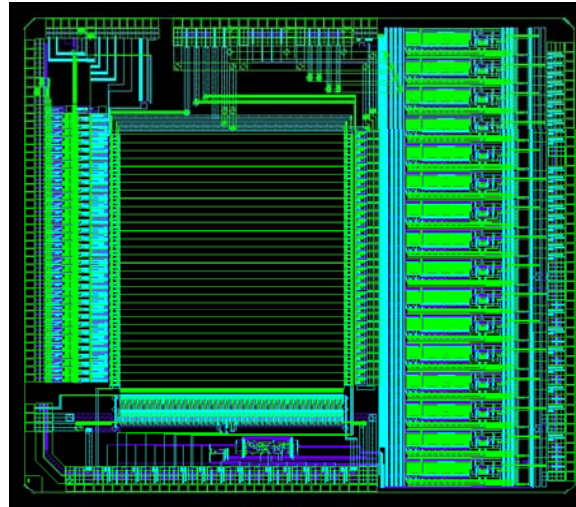
## *PASCAL 64 channels*

- low noise 300 e- rms
- 10 bit dynamic range
- 256 deep analog memory
- On chip 16/32 10 bit ADC

*10 000 chips for ALICE SDD tracker*

*0.25  $\mu\text{m}$  CMOS, 1P, 3M*

*"Special" design rules*



# Front end design other examples Calorimeter preshower

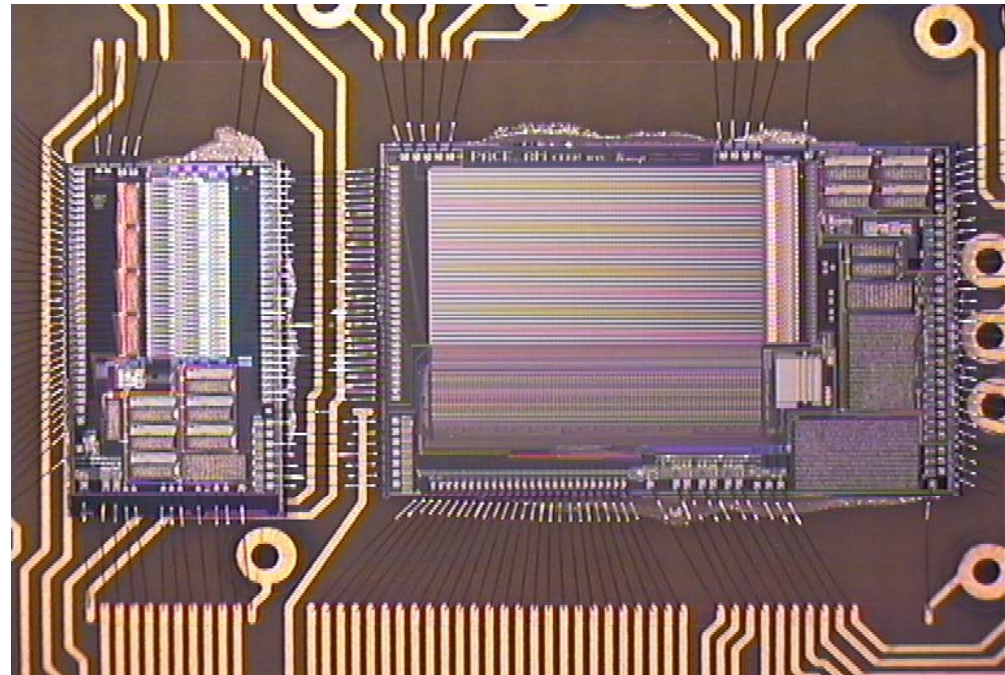
## *PACE 32 channels*

- low noise
- 12 bit dynamic range
- 192 deep analog memory
- serial analog read-out

*> 100,000 chips in CMS ECAL*

*0.25  $\mu\text{m}$  CMOS, 1P, 3M*

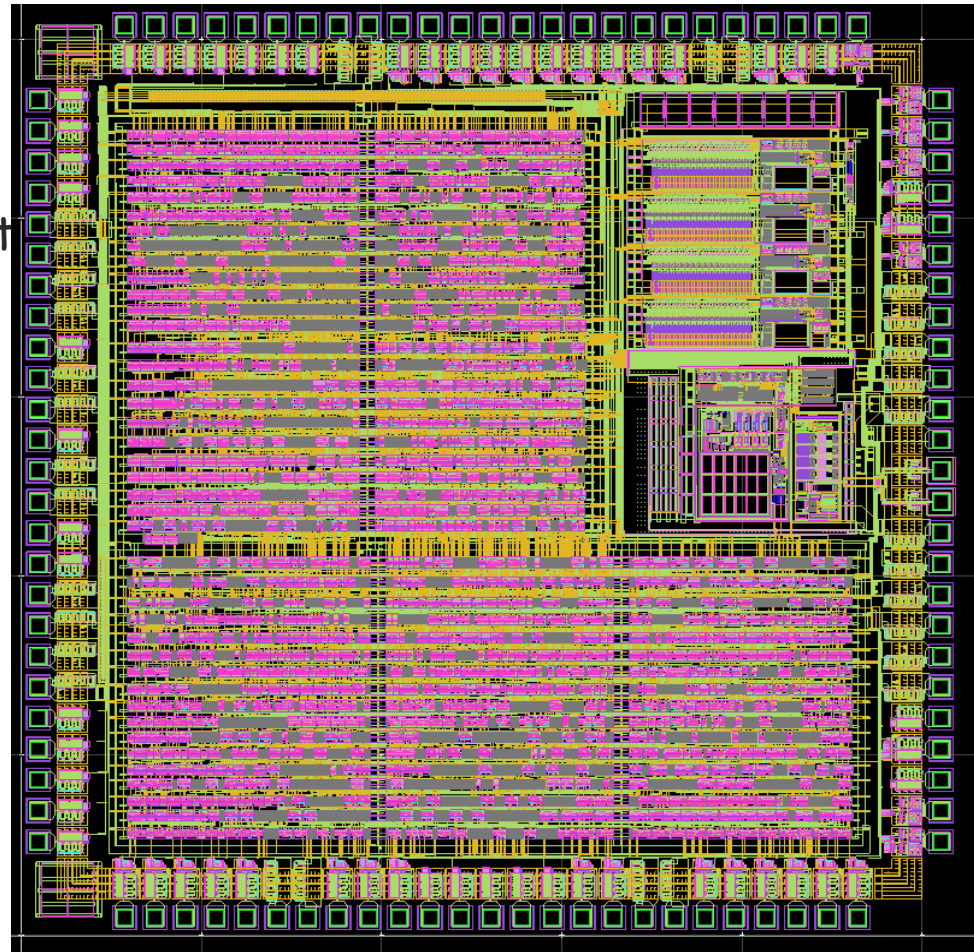
*"Special" design rules*





# ASIC for LHC timing distribution

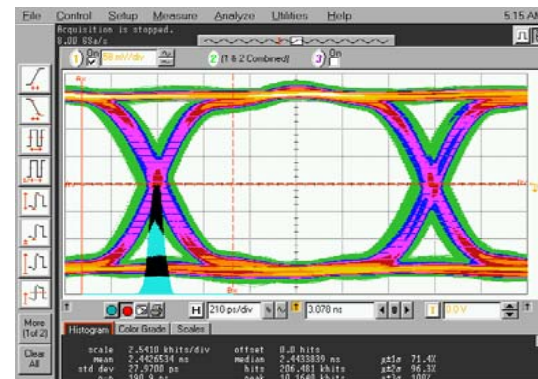
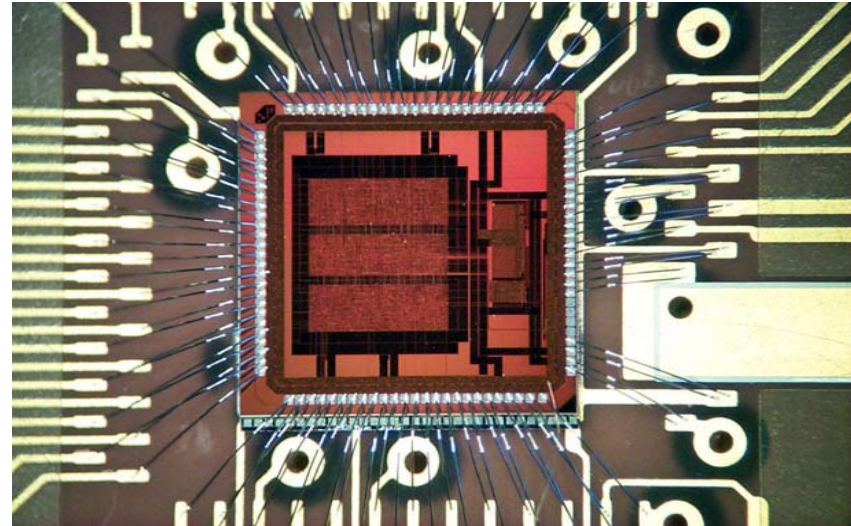
- ◆ TTCrx: 40 MHz opto-receiver for high precision clock distribution
  - ◆ 1 to 30,000 optical fan-out
  - ◆ 100 ps resolution
  - ◆ low jitter
- ◆ DMILL technology
  - ◆ rad-hard
  - ◆ 0.8  $\mu\text{m}$  BiCMOS
  - ◆  $\sim 5 \times 5 \text{ mm}^2$



# High Speed Serializer, radiation hardened

## *Gigabit Optical Link (GOL)*

- ◆ 0.8 and 1.60 Gb/s optical link
- ◆ Unidirectional
- ◆ < 300 mW
- ◆ G-Link and Gigabit Ethernet protocol
- ◆ Redundant logic



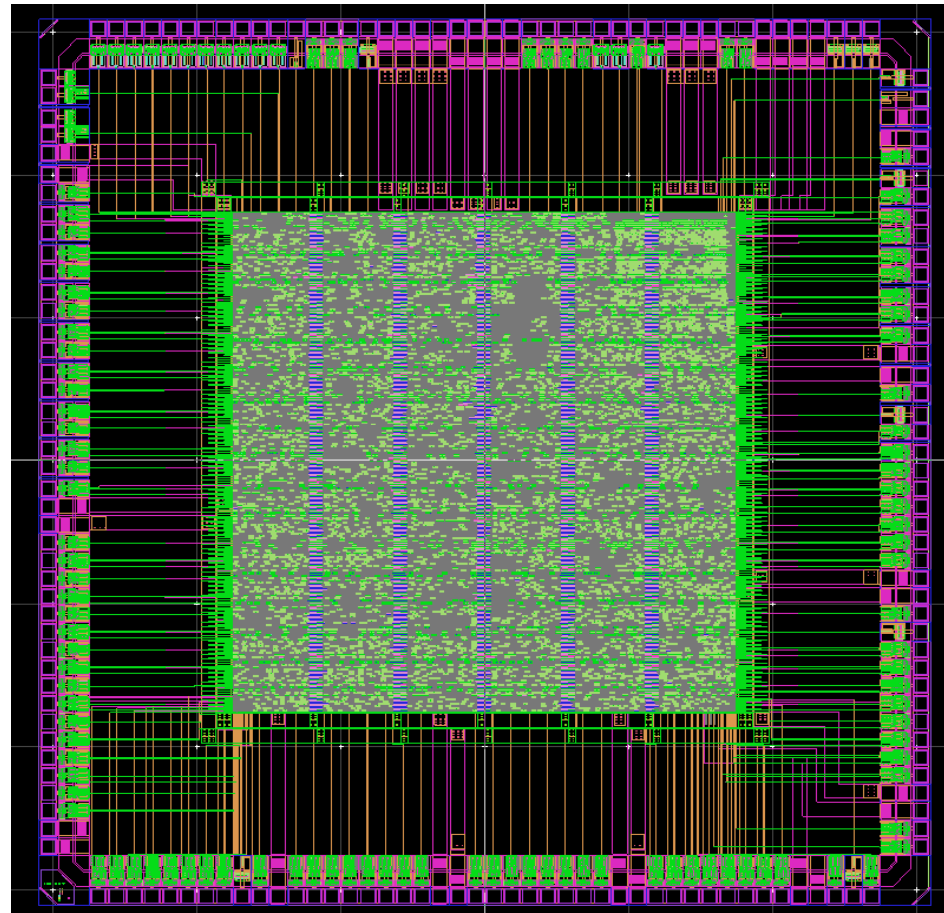
# Slow Control Network Controller

## *CCU25: Radiation Tolerant Network Controller*

- Token-Ring-like Protocol with redundancy
- 40 Mb/s (LHC frequency)
- Reconfigurable
- Support for multiple user-buses

### *Chip:*

- 100% digital
- special library
- 120,000 gates
- SEU redundancy on critical blocks

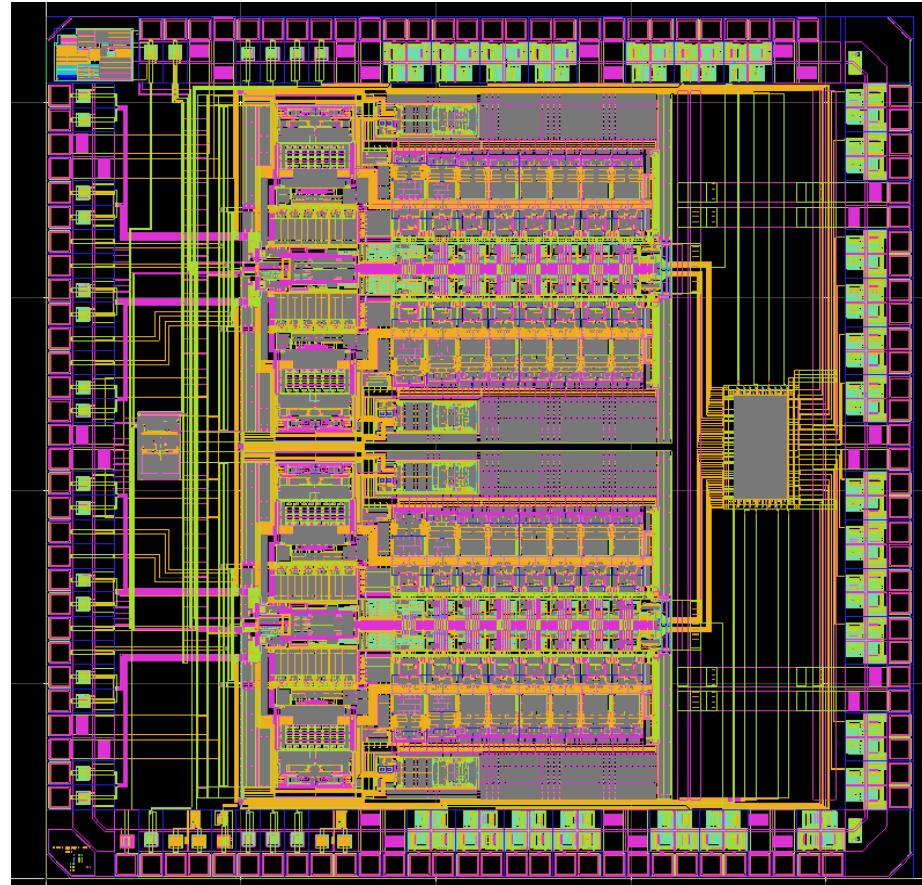




# 12 Bit 40 Ms/s Converter, radiation hardened

## *4 channels, 12 bit 40 MS/s Analog to Digital Converter*

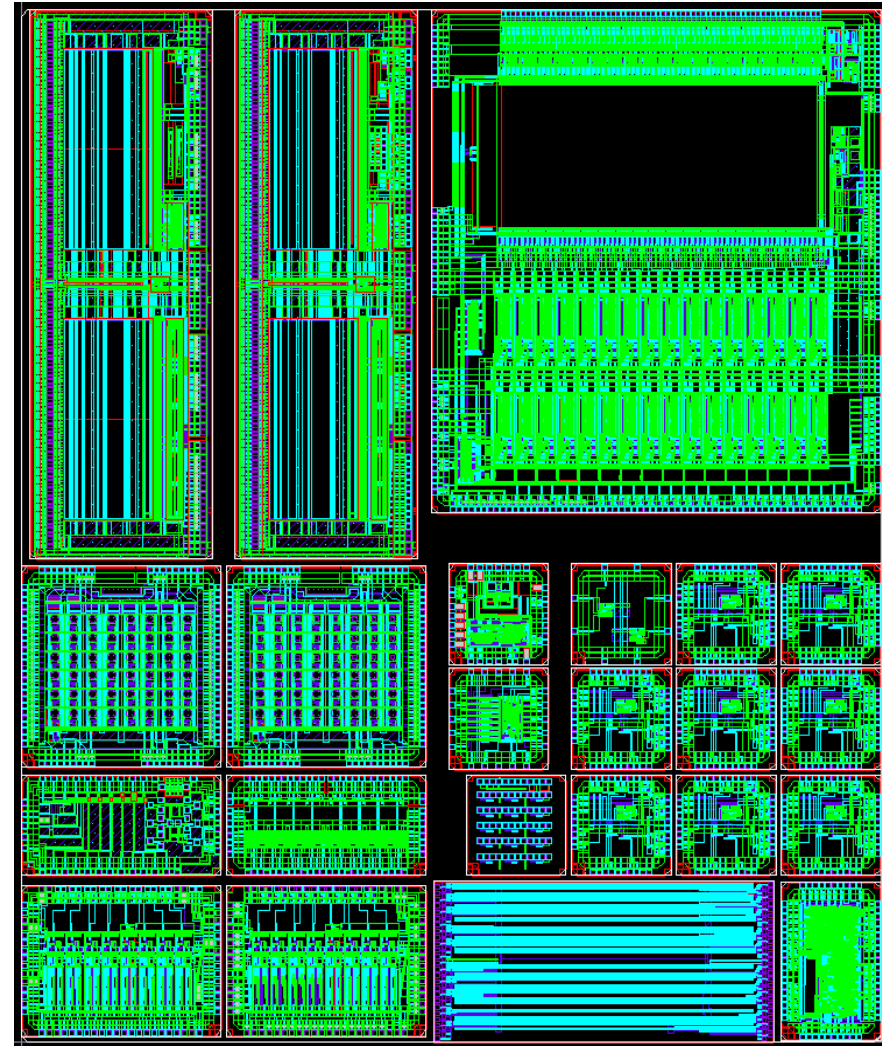
- < 500 mW
- several modes of operation
  - 4xADC @ 12 bit
  - 1xADC @ 14 bit
- Rad-tolerant
- 4x4 mm<sup>2</sup>



# CERN microelectronics MPW

## *Organization of MPW for High Energy Physics community and TT*

- European and US Institutes, ~20 Design Groups
- 12 MPW  
20 production runs in 4 years



# Radiation hardening

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*Radiation hardness characteristic has driven the technology choice for LHC*

- 3 technologies selected in late 90's
  - DMILL from Atmel
    - BiCMOS 0.8  $\mu\text{m}$  technology with rad-tolerance “by process”
  - 0.25  $\mu\text{m}$  ‘standard’ CMOS
    - rad-tolerance “by design”
  - ST Microelectronics Bipolar process
    - For power device: radiation hardened regulator

*Special libraries (digital and analog) developed for LHC applications*

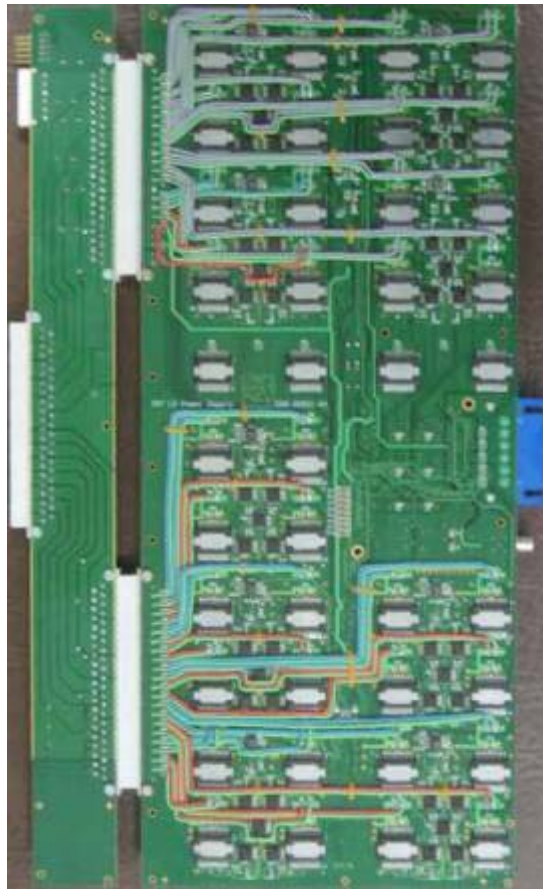




# Radiation hardened voltage regulator in ATLAS board

*Developed in partnership with ST Microelectronics*

- For LHC, spin off for aerospace industry



# Signal processing telecom – HEP and single photon camera

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## *Telecom*

- Information is contained in the modulation of a carrier
- Source of data is analogue
  - Voice, video etc.. communication
- Signal processing
  - In frequency domain

## *HEP*

- Information comes from quantum events
  - Single charge particle or photon hits a sensor
- Source of data is a quantum charge packet
  - Binary information
- Signal processing
  - Time domain: event time, number of hits



# Applications of ASICs developed for HEP

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## *Fields*

- Life science
- Medical imaging
- X-ray and electron based instrumentation

## *Key performance*

- Single quanta detection
  - Visible photon : camera for life science
  - X-ray photon : radiography
  - Gamma photon: nuclear medicine
- Architecture
  - Linear multichannel array
  - Pixel array
  - Signal processing
    - Counting
    - Time correlated measurement



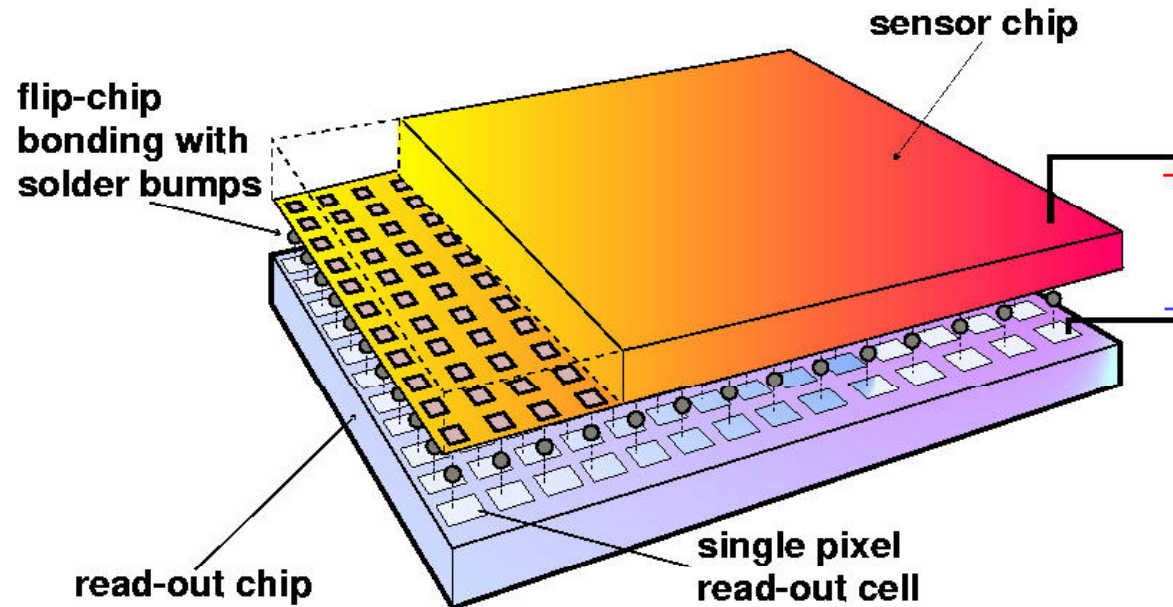


# Medipix

*Photon counting readout chip used for medical, biological and physics applications.*

*The chip consists in an active matrix of 256x256 photon counting pixels.*

- ◆ > 10 million transistors,
- ◆ 55 micron pixel cell



# Life science applications

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## *Standard imaging*

- Imaging ensemble of molecules gives access only to averaged images
- one miss
  - Static heterogeneity of molecules distribution
  - Dynamic distribution of molecules
  - Existence of several different molecule species

## *Time-correlated single photon spectrometry*

- Has revolutionized imaging in biology
- Labeling molecules (DNA, proteins) in living cells with fluorophores



# Fluorescence Imaging technique

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## *Fluorescence imaging*

- Each visible photon quanta is detected and counted in a pixel or correlated with its time stamp

## *Single quanta detectors for visible photon*

- Photomultiplier
- Microchannel plate
- Hybrid Photo detector
- SPAD

## *Non spectroscopy imaging*

- Counting number of photons/pixel
  - Fast camera
  - wide-field microscopy





# Time-correlated single photon in life science

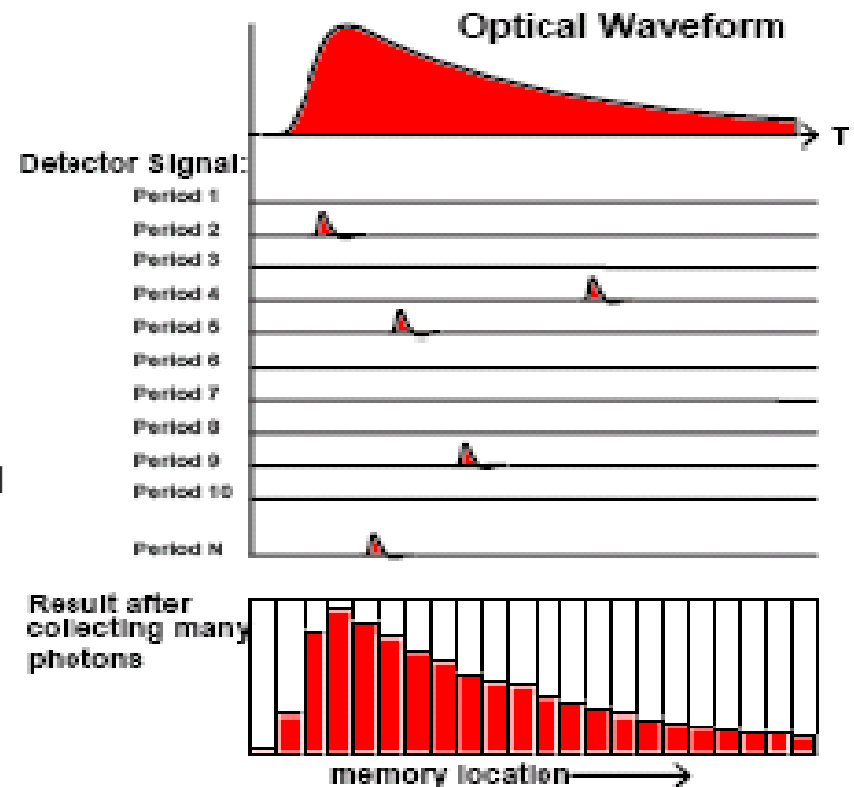
## *Some Applications*

- Ultra-Fast Recording of Optical Waveforms, fast camera
- Fluorescence Lifetime Measurements
- Detection and Identification of Single Molecules
- DNA Sequencing
- Optical Tomography
- Fluorescence Lifetime Imaging
- FLIM and FRET fluorescence microscopy

## *Benefits*

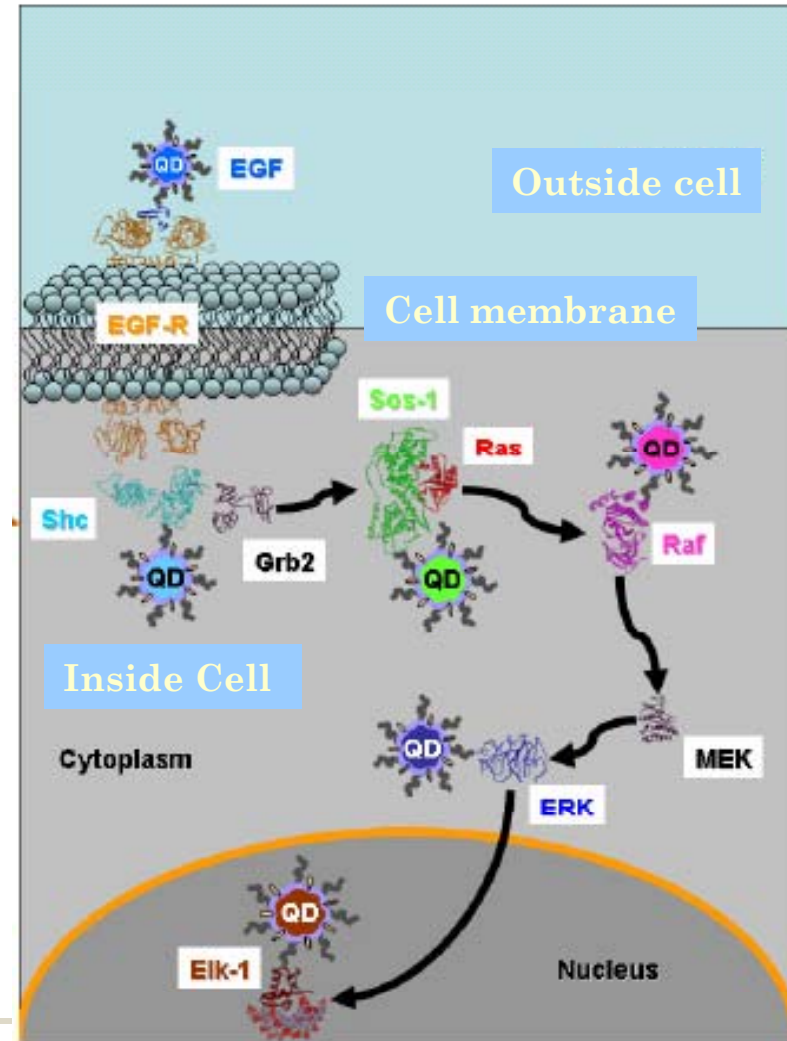
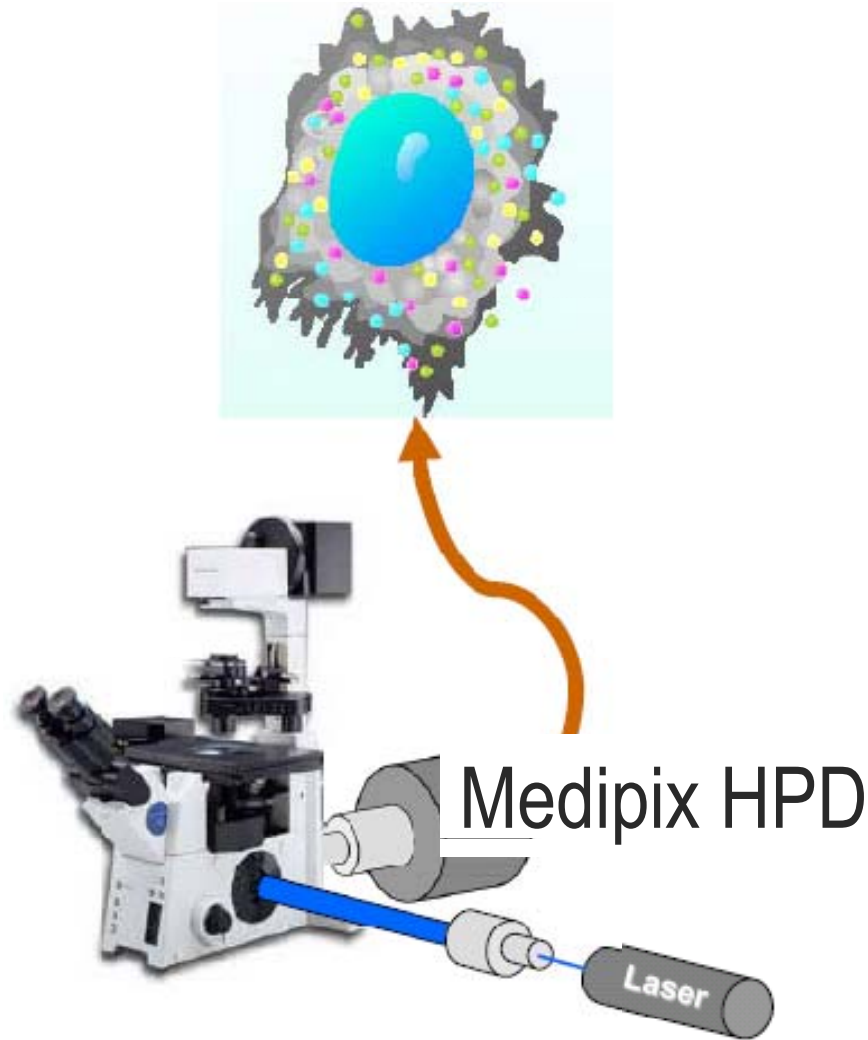
- Ultra-high Time Resolution - 25 ps fwhm in time correlated mod
- Ultra-High Sensitivity - down to the single photon level
- Short measurement Times
- High dynamic range - High Linearity in counting mode
- Signal-to-Noise Ratio - Limited by Photon Statistics only
- High Gain Stability, absolute calibration
- Suppression of Detector Leakage Currents

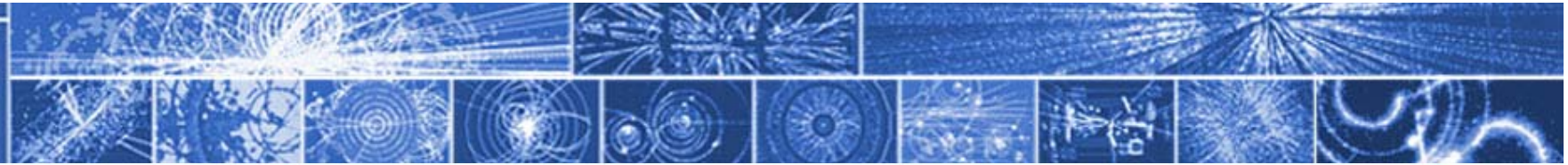
Principle of single photon time-correlated spectroscopy



# Single molecule imaging with fast camera

Imaging cellular processes at the sub-cellular or molecular levels



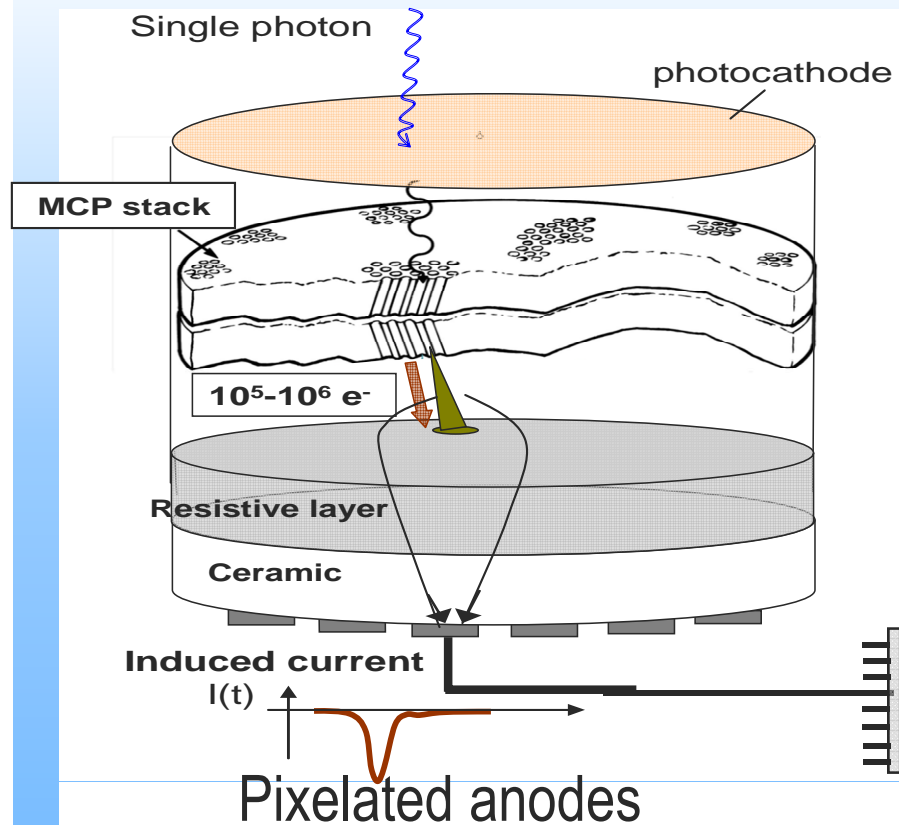


# CERN

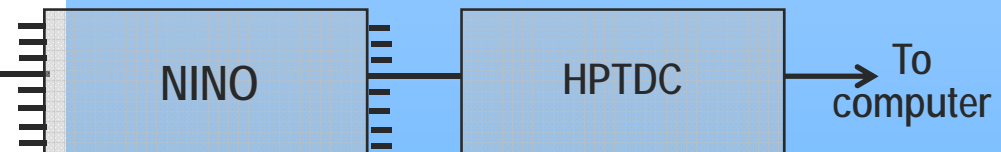
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## Single photon counting and imaging with microchannel plate



- The front end NINO read out a pixelated micro channel plate
- Signal from NINO are "time stamped" by the HPTDC
- Following signal processing is performed in FPGA by user





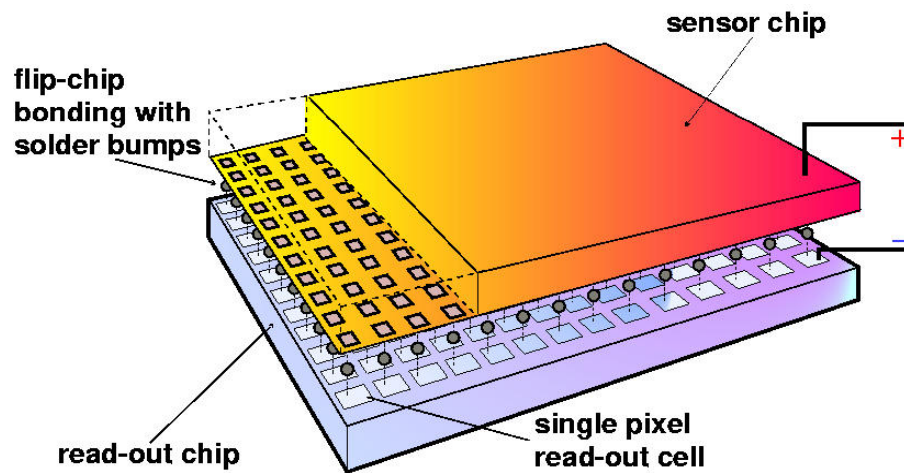
# Medical imaging

## Counting systems in medicine

- X-ray radiography
- CT, SPECT tomography

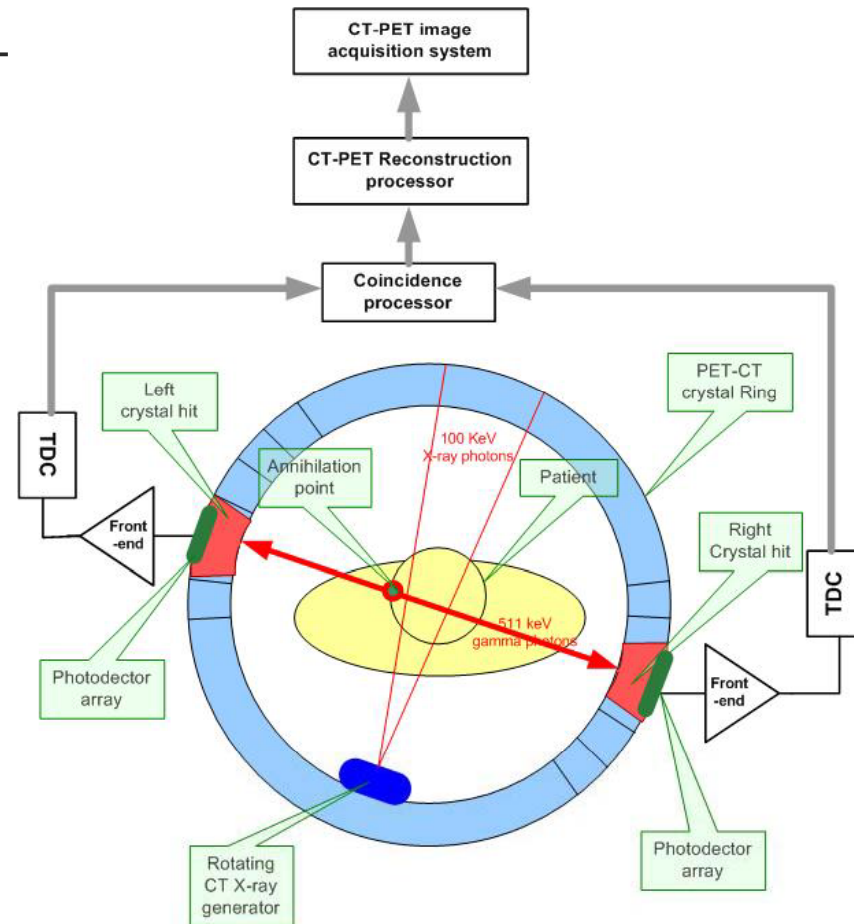
### Medipix: X-ray Photon counting readout chip

- The chip consists in an active matrix of 256x256 photon counting pixels.
  - ◆ 10 million transistors, 55 micron pixel cell



## Time correlated systems in nuclear

PET



# How to do Technology Transfer in microelectronics

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## *Direct use of existing ASIC*

- Recommended for low volume
- Analysis of the ASIC integration in the instrument
- Needs adaptation on electronics boards only
- With or without a new wafer production

## *Use of existing ASIC design*

- With slight design changes
- Cost: design time + wafer production + test

## *Use of existing functional blocks*

- New ASIC design with existing know-how
- Expensive and long development time

## *Partnership with industry*

- Develop in common a new product
- With ST Microelectronics on radiation hard voltage regulator

## *Partnership in a scientific collaboration*

- Medipix
- EU projects

## *For a new instrument*

- Do not underestimate system integration, even if components are available!
  - Establish a common language between technology users and technology providers
  - Technology compatibility, to sensor, to data acquisition



# SUMMARY

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*CERN has several cases of successful technology transfer of ASIC technology*

*The main fields of technology transfer of ASICs based on single quanta detection*

- Life science and imaging in medicine
- Material science instrumentation and aerospace

*Two main domain of applications*

- Single photon counting system
- Time resolved single photon spectroscopy

*Development of sophisticated ASICs demand resources and time*

- Use of existing ASIC is the best approach for low volume, limited resources and short time to market.
- Use of existing blocks to develop a new ASIC is the way to go, it needs much larger resources and time.

